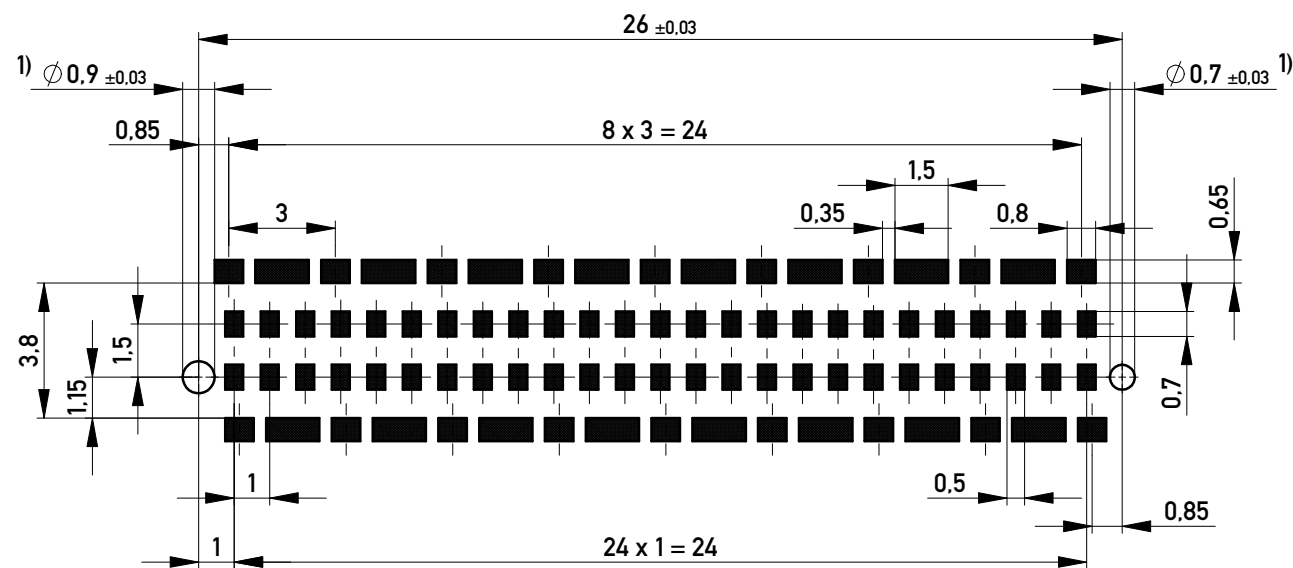
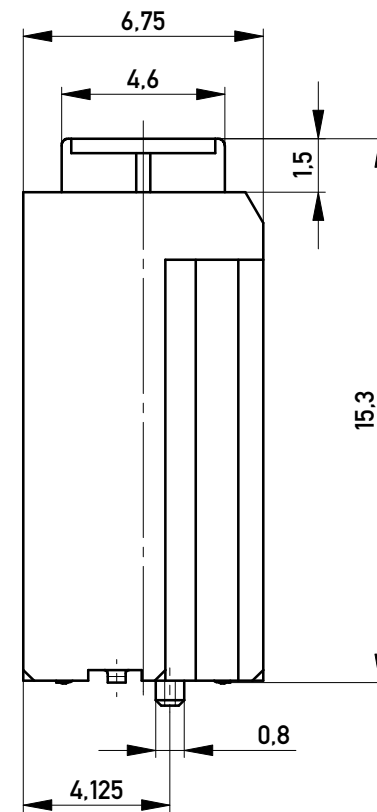


Leiterplatten-Layout Vorschlag / recommended PCB-layout

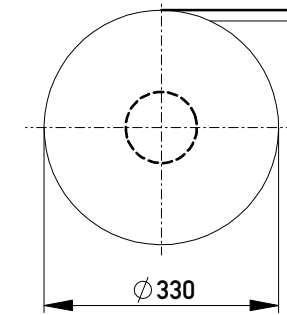


1) Durchmesser des Bohrers / drill tool

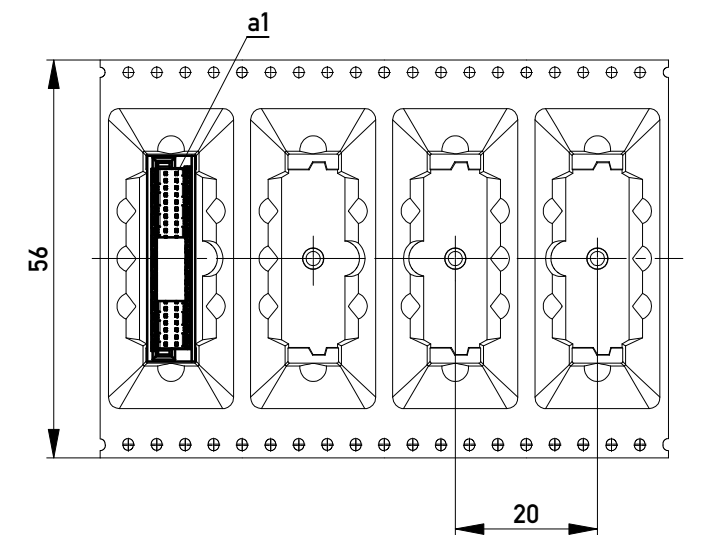
Für weitere Layout Details bitte
 Applikations Schrift MicroSpeed beachten.
 For further layout details please consider
 MicroSpeed application note.



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
 tape on reel packaging according to DIN IEC 60286-3
 Verpackungseinheit: 170 Stück
 packaging unit: 170 pcs



Abspulrichtung - Reel off direction



Anforderungsstufe 1
 performance level 1

Kontaktbereich vergoldet
 mating area gold plating

Anschlussbereich verzinkt 4-6 µm
 terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
 coplanarity area of termination ≤ 0,1 mm

Information: All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.	Tolerances All Dimensions in mm	Scale	5:1
		Designation	M10 SMD BM EMV, 50 polig M10 SMD BM EMV, 50 pin
Index	Date	www.ERNI.com	
		484290	
Class		MSPEED	

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